

**Abstract:**

Optical subassembly and projection objective in semiconductor lithography

(Figure 4)

An optical subassembly with an optical element, for example a mirror element (7), has an optical surface (9) and bearing points (12) arranged on the circumference. The optical element (7) is connected to a mount (13) at the bearing points (12) via connecting elements (14, 15, 16, 17, 18). Stress-decoupling cutouts, for example curved slots (11), are provided between the optical surface (9) and the bearing points (12).

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